

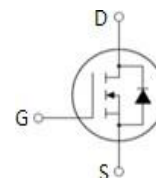


FEATURES

- Proprietary New Trench Technology
- Low Gate Charge Minimize Switching Loss
- Fast Recovery Body Diode

Applications

- High efficiency DC/DC Converters
- Synchronous Rectification
- UPS Inverter



Product Summary

| | | |
|-----------------------------|-----|------------|
| V_{DSS} | 85 | V |
| $R_{DS(ON)-Typ@V_{GS}=10V}$ | 9.5 | m Ω |
| I_D | 90 | A |

Absolute Maximum Ratings $T_C = 25^\circ C$, unless otherwise noted

| Parameter | Symbol | Value | | Unit |
|--|----------------|----------|--------|------------|
| | | TO-220F | TO-220 | |
| Drain-Source Voltage ($V_{GS} = 0V$) | V_{DSS} | 500 | | V |
| Continuous Drain Current | I_D | 90 | | A |
| Pulsed Drain Current (note1) | I_{DM} | 340 | | A |
| Gate-Source Voltage | V_{GSS} | ± 30 | | V |
| Single Pulse Avalanche Energy (note2) | E_{AS} | 570 | | mJ |
| Single Pulse Avalanche Current (note1) | I_{AS} | 36.6 | | A |
| Repetitive Avalanche Energy (note1) | E_{AR} | 342 | | mJ |
| Power Dissipation ($T_C = 25^\circ C$) | P_D | 55 | 43 | W |
| Operating Junction and Storage Temperature Range | T_J, T_{stg} | -55~+150 | | $^\circ C$ |

Thermal Resistance

| Parameter | Symbol | Value | | Unit |
|---|------------|---------|--------|------|
| | | TO-220F | TO-220 | |
| Thermal Resistance, Junction-to-Case | R_{thJC} | 5 | 4.2 | K/W |
| Thermal Resistance, Junction-to-Ambient | R_{thJA} | 62.5 | 60 | |



| Specifications $T_J = 25^\circ\text{C}$, unless otherwise noted | | | | | | |
|--|--------------|--|-------|------|-----------|------------|
| Parameter | Symbol | Test Conditions | Value | | | Unit |
| | | | Min. | Typ. | Max. | |
| Drain-to-Source Breakdown Voltage | BV_{DSS} | $V_{GS}=0V, I_D=250\mu A$ | 80 | -- | -- | V |
| Drain-to-Source Leakage Current | I_{DSS} | $V_{DS}=80V, V_{GS}=0V$ | -- | -- | 1 | μA |
| | | $V_{DS}=64V, V_{GS}=0V, T_J=125^\circ\text{C}$ | -- | -- | 100 | |
| Gate-to-Source Leakage Current | I_{GSS} | $V_{GS}=\pm 20V, V_{DS}=0V$ | -- | -- | ± 100 | nA |
| Gate Threshold Voltage | $V_{GS(TH)}$ | $V_{DS}=V_{GS}, I_D=250\mu A$ | 2.0 | -- | 4.0 | V |
| Static Drain-to-Source On-Resistance | $R_{DS(ON)}$ | $V_{GS}=10V, I_D=40A$ | -- | 9.5 | 12 | m Ω |
| Dynamic | | | | | | |
| Input Capacitance | C_{iss} | $V_{GS} = 0V,$ $V_{DS} = 25V,$ $f = 1.0\text{MHz}$ | -- | 2728 | -- | pF |
| Output Capacitance | C_{rss} | | -- | 782 | -- | |
| Reverse Transfer Capacitance | C_{oss} | | -- | 339 | -- | |
| Total Gate Charge | Q_g | $V_{DD}=40V,$ $I_D=40A, V_{GS}=0 \text{ to } 10V$ | -- | 164 | -- | nC |
| Gate-to-Source Charge | Q_{gs} | | -- | 15 | -- | |
| Gate-to-Drain (Miller) Charge | Q_{gd} | | -- | 71 | -- | |
| Turn-on Delay Time | $t_{d(ON)}$ | $V_{DD}=40V,$ $I_D=10A,$ $V_{GS}= 10V$ $R_G=25\Omega$ | -- | 50 | -- | nS |
| Rise Time | t_{rise} | | -- | 106 | -- | |
| Turn-Off Delay Time | $t_{d(OFF)}$ | | -- | 408 | -- | |
| Fall Time | t_{fall} | | -- | 183 | -- | |
| Drain-Source Body Diode Characteristics | | | | | | |
| Continuous Source Current (note2) | I_{SD} | Integral PN-diode in MOSFET | -- | -- | 85 | A |
| Pulsed Source Current (note2) | I_{SM} | | -- | -- | 340 | |
| Diode Forward Voltage | V_{SD} | $I_S=75A, V_{GS}=0V$ | -- | -- | 1.2 | V |
| Reverse recovery time | t_{rr} | $V_{GS}=0V, I_F=10A,$ $d_iF/dt=100A/\mu s$ | -- | 100 | -- | ns |
| Reverse recovery charge | Q_{rr} | | -- | 410 | -- | nC |

Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. $L=1\text{mH}, V_{DD} = 50V, R_G = 25 \Omega$, Starting $T_J = 25^\circ\text{C}$
3. Pulse Test: Pulse width $\leq 300\mu s$, Duty Cycle $\leq 1\%$



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Typical Output Characteristics

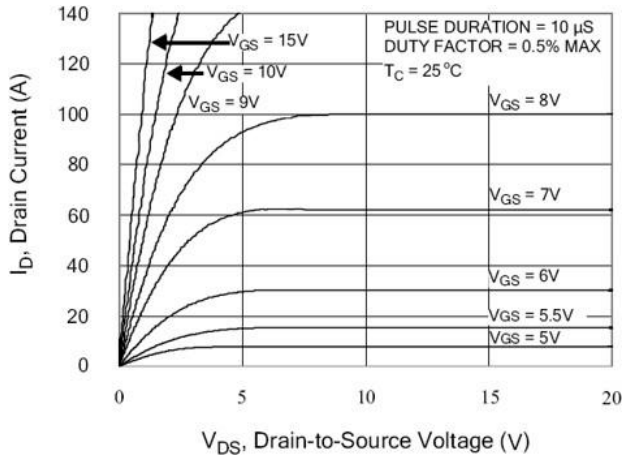


Figure 2. Maximum Power Dissipation vs Case Temperature

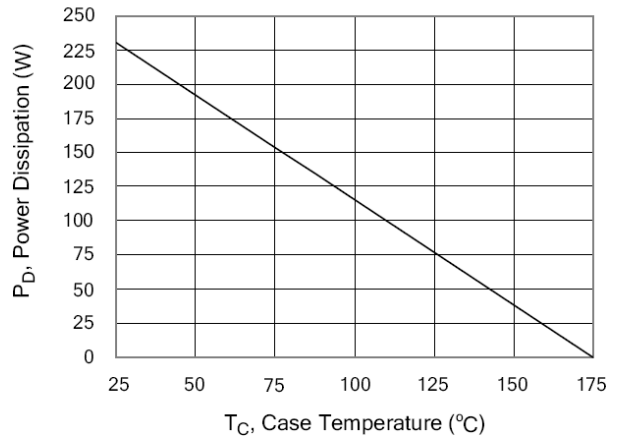


Figure 3. Maximum Continuous Drain Current vs Case Temperature

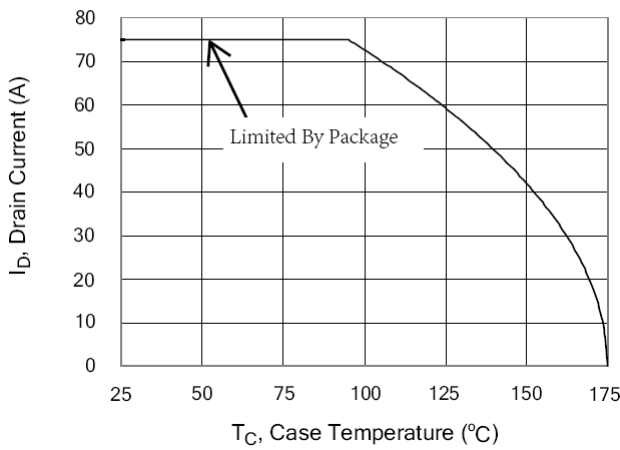


Figure 4. Typical Drain-to-Source ON Resistance vs Gate Voltage and Drain Current

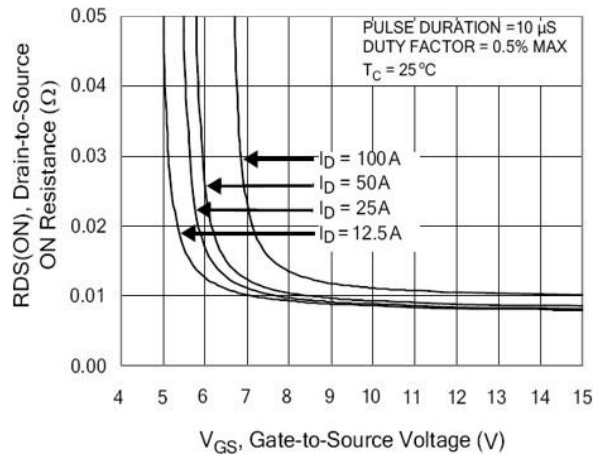


Figure 7. Typical Drain-to-Source ON Resistance vs Drain Current

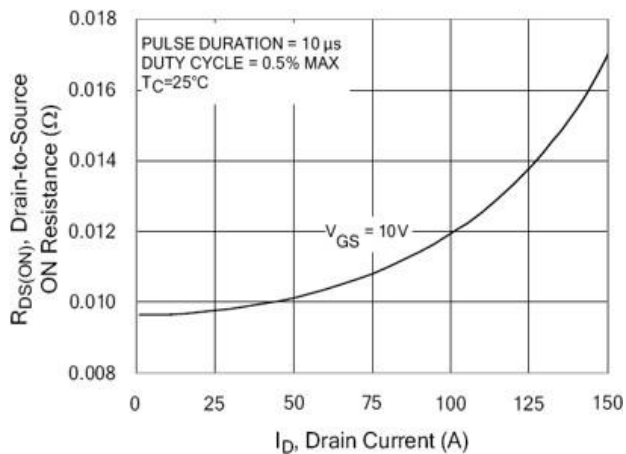
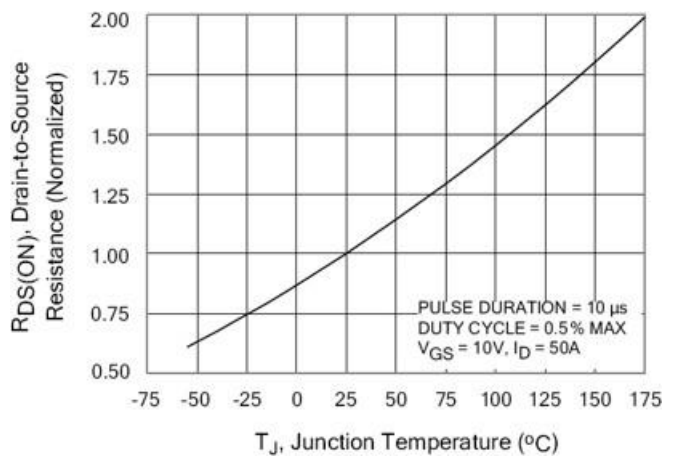


Figure 8. Typical Drain-to-Source ON Resistance vs Junction Temperature





Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. Capacitance

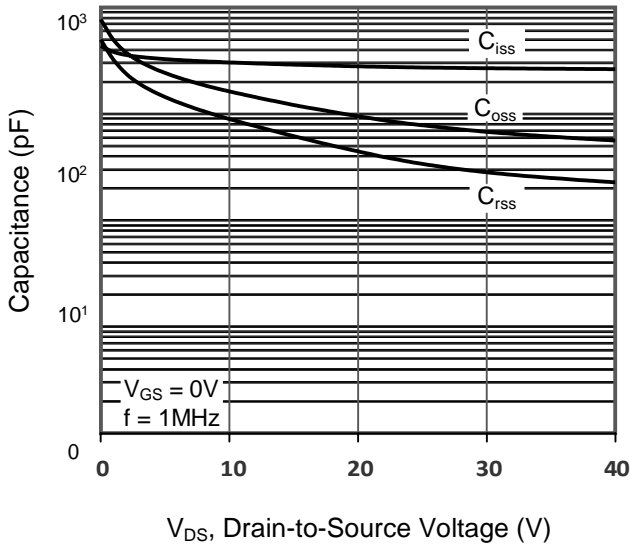


Figure 8. Gate Charge

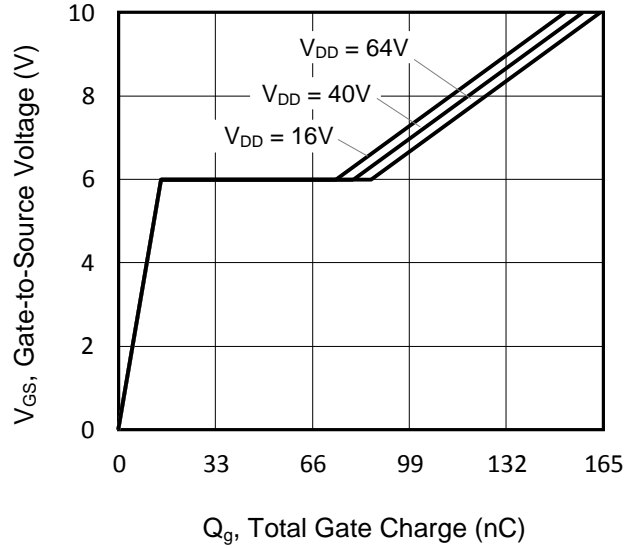


Figure 9. Transient Thermal Impedance TO-251, TO-252, TO-220

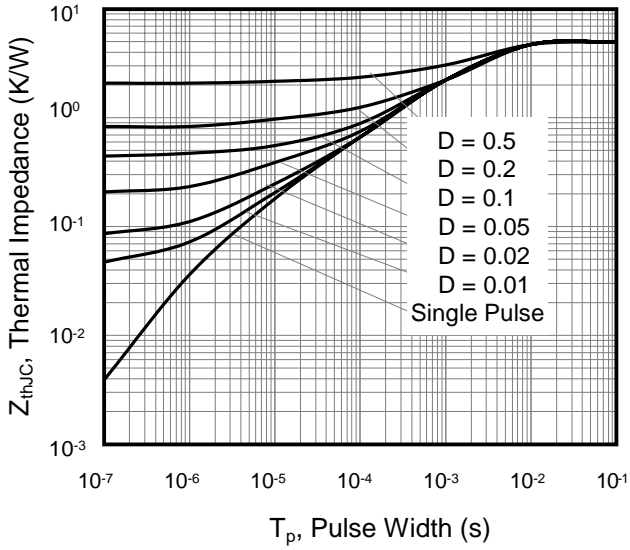


Figure 10. Transient Thermal Impedance TO-220F

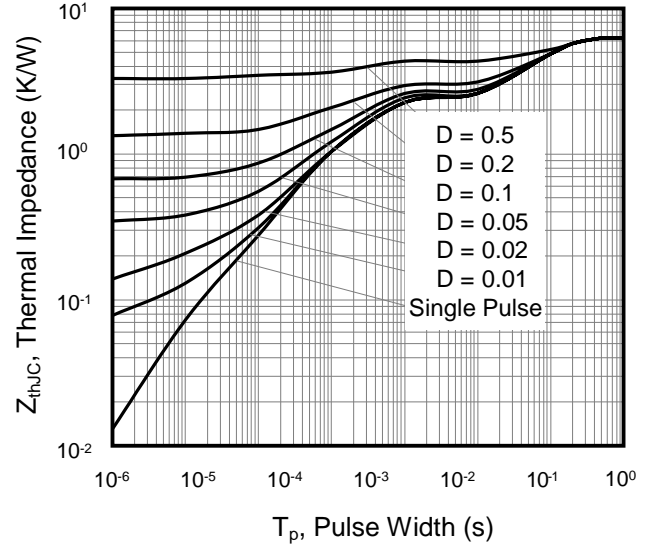




Figure A: Gate Charge Test Circuit and Waveform

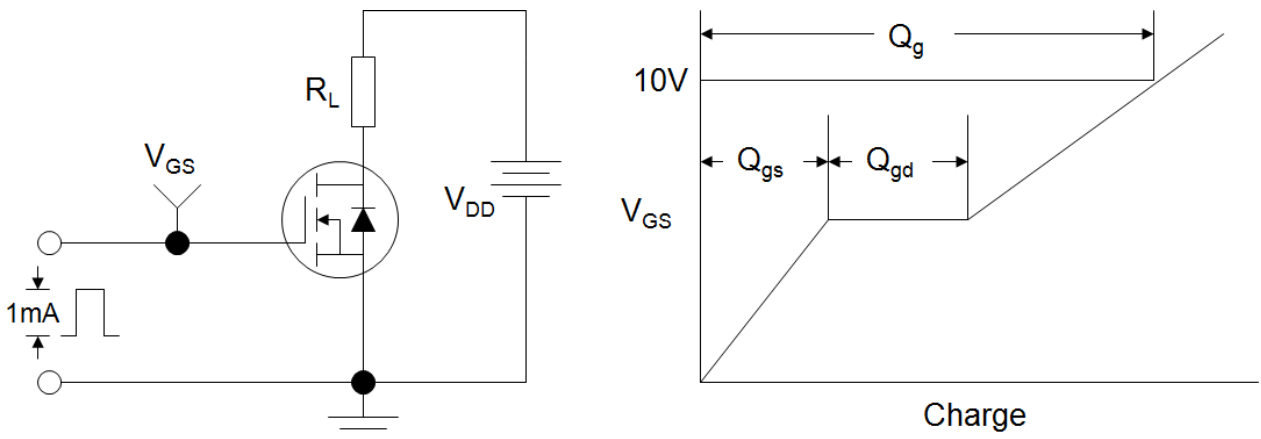


Figure B: Resistive Switching Test Circuit and Waveform

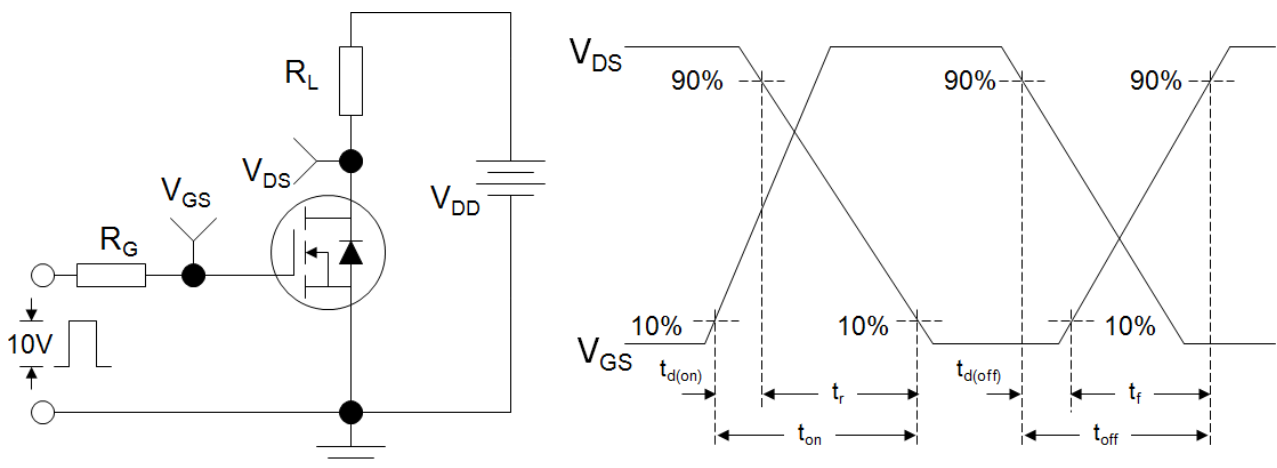
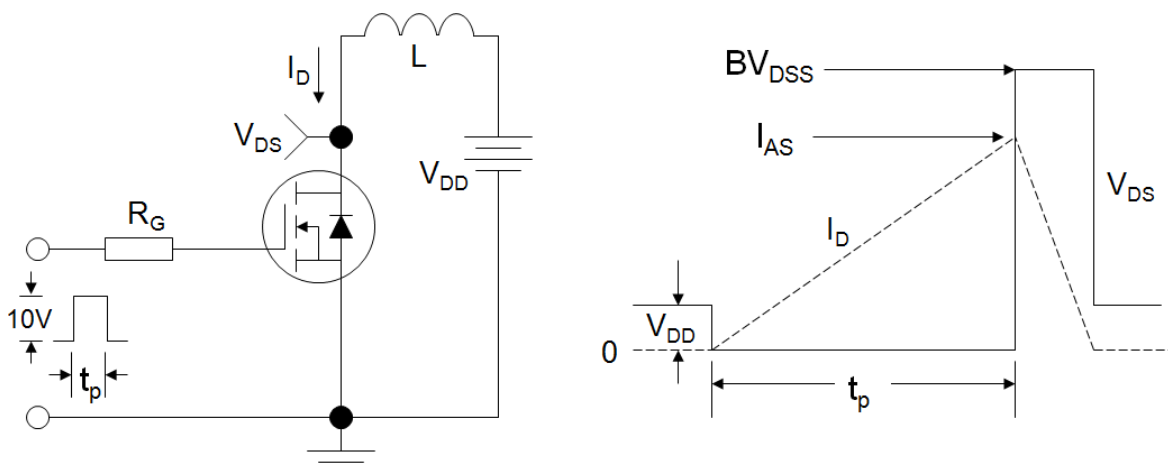


Figure C: Unclamped Inductive Switching Test Circuit and Waveform





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